



VMDSEMI

**VSTD065R44ANA**

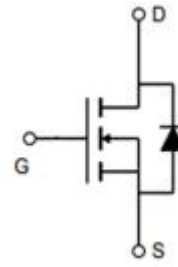
**Datasheet**



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**General Description**
**Symbol**

$V_{(BR)DSS}$	$R_{DS(ON)_{max}}$	$I_D$
650V	440mΩ@10V	10A



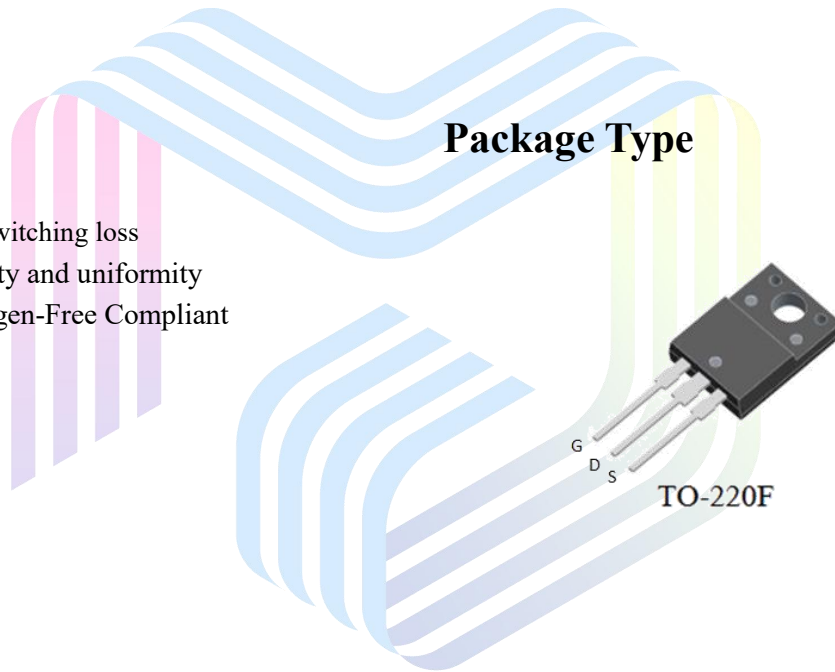
Symbol of VSTD065R44ANA

**Features**

- Extremely low switching loss
- Excellent stability and uniformity
- RoHS and Halogen-Free Compliant

**Package Type**
**Application**

- PC power
- LED lighting
- Telecom power
- Server power
- Solar/UPS



Package Type of VSTD065R44ANA

**Ordering Information**

Product Name	Package	Marking
VSTD065R44ANA	TO-220F	STD065R44ANA

## Absolute Maximum Ratings

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DS}$	650	V
Gate-Source Voltage	$V_{GS}$	±30	V
Continuous Drain Current <sup>Note 1</sup> , $T_C=25^\circ\text{C}$	$I_D$	10	A
Pulsed Drain Current <sup>Note 2</sup> , $T_C=25^\circ\text{C}$	$I_{D, pulse}$	30	A
Continuous Diode Forward Current <sup>Note 1</sup> , $T_C=25^\circ\text{C}$	$I_S$	10	A
Diode Pulsed Current <sup>Note 2</sup> , $T_C=25^\circ\text{C}$	$I_{S, pulse}$	30	A
Max Power Dissipation <sup>Note 3</sup> , $T_C=25^\circ\text{C}$	$P_D$	77	W
Avalanche Current, Single Pulse <sup>Note 4</sup>	$I_{AS}$	5.6	A
Avalanche Energy, Single Pulse <sup>Note 4</sup>	$E_{AS}$	317.3	mJ
MOSFET dv/dt ruggedness, $V_{DS}=0\sim 480\text{V}$	dv/dt	50	V/ns
Reverse diode dv/dt, $V_{DS}=0\sim 480\text{V}$ , $I_{SD}\leq I_D$	dv/dt	15	V/ns
Operation and storage temperature	$T_J, T_{STG}$	-55 to 150	°C

## Thermal Resistance

Parameter	Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$		1.63		°C/W
Thermal Resistance, Junction-to-Ambient <sup>Note 5</sup>	$R_{\theta JA}$		62		

## Notes:

Note1: Calculated continuous current based on maximum allowable junction temperature.

Note2: Pulse width limited by safe operating area.

Note3: Based on max. junction temperature, using junction-case thermal resistance.

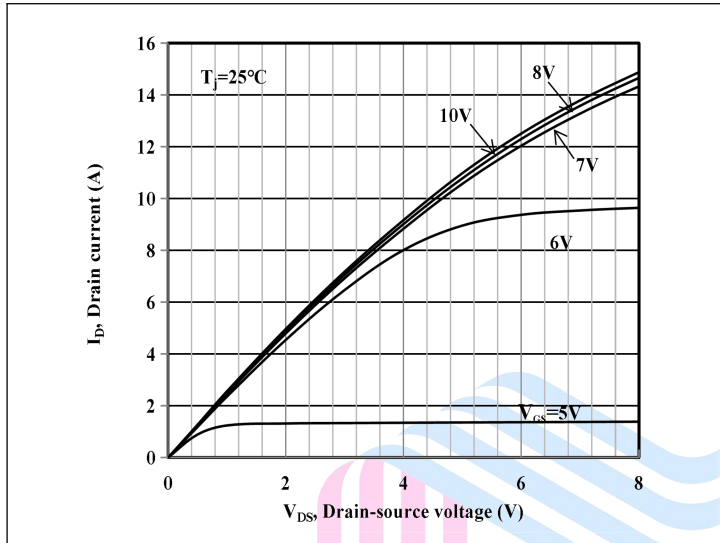
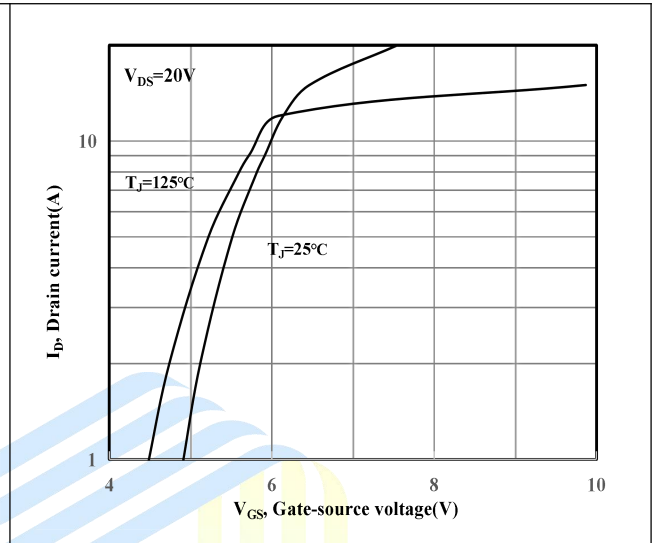
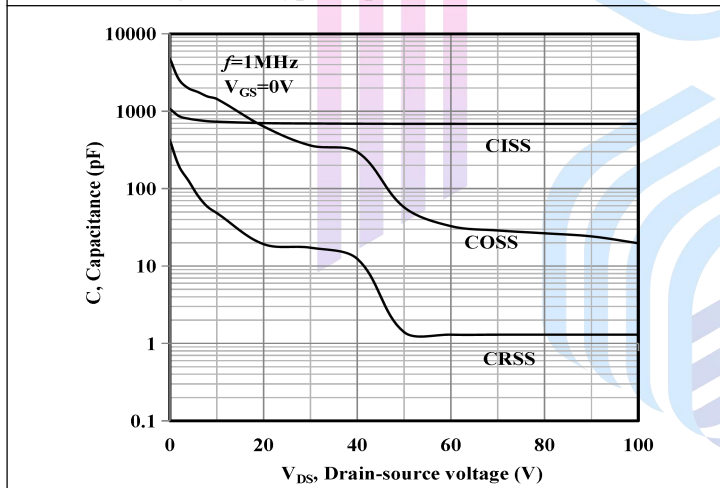
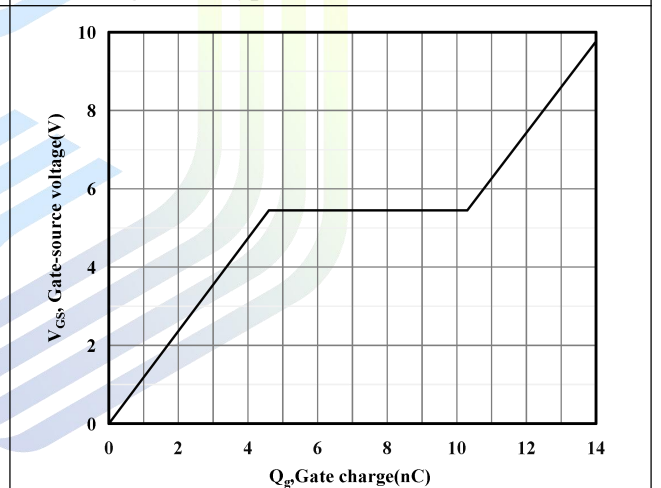
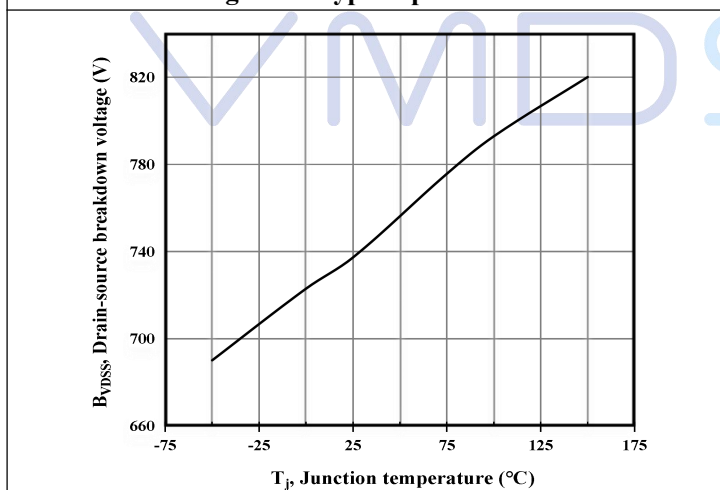
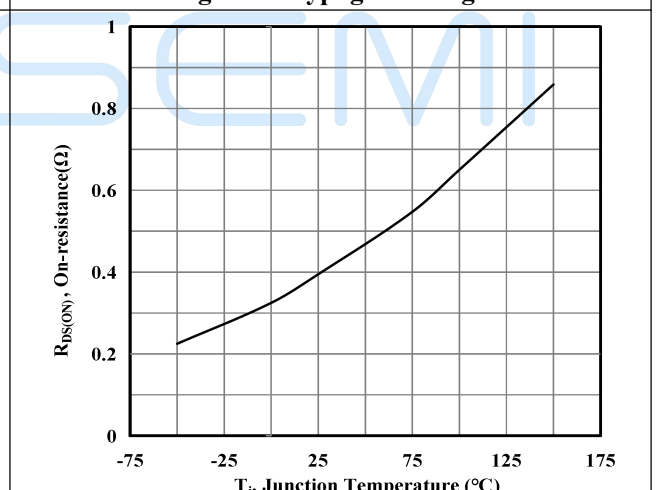
Note4:  $V_{DD}=50\text{V}$ ,  $V_{GS}=10\text{V}$ ,  $L=20\text{mH}$ , starting  $T_A=25^\circ\text{C}$ .

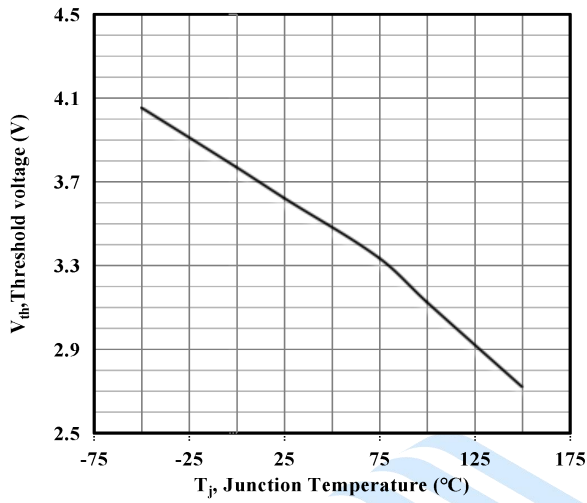
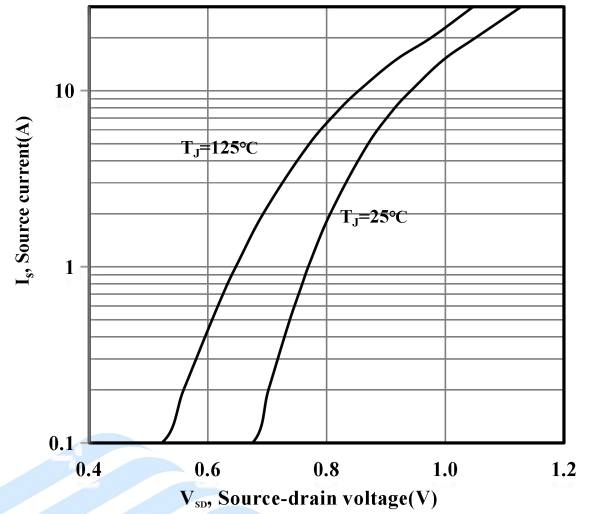
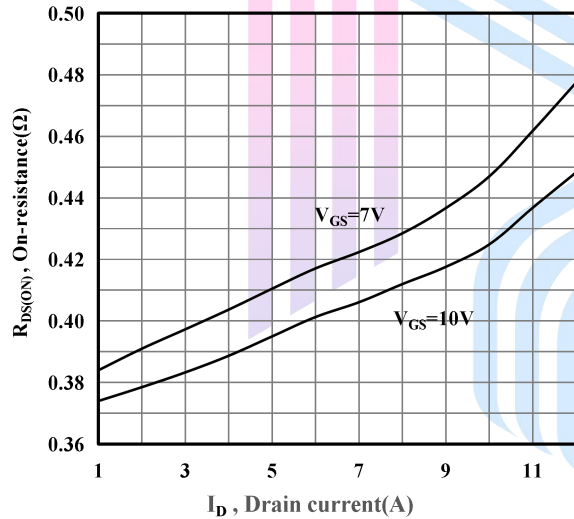
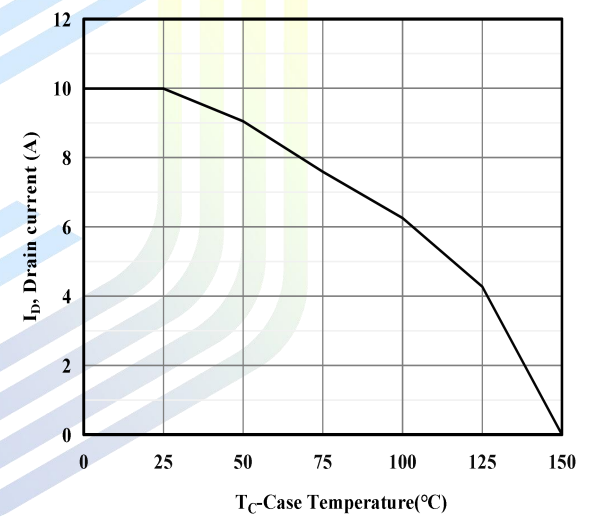
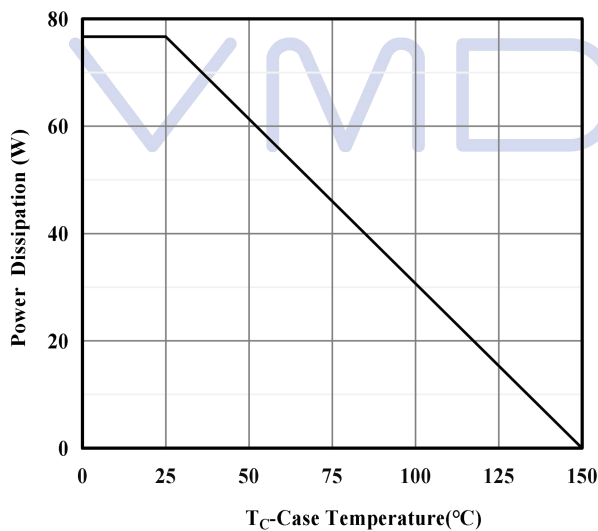
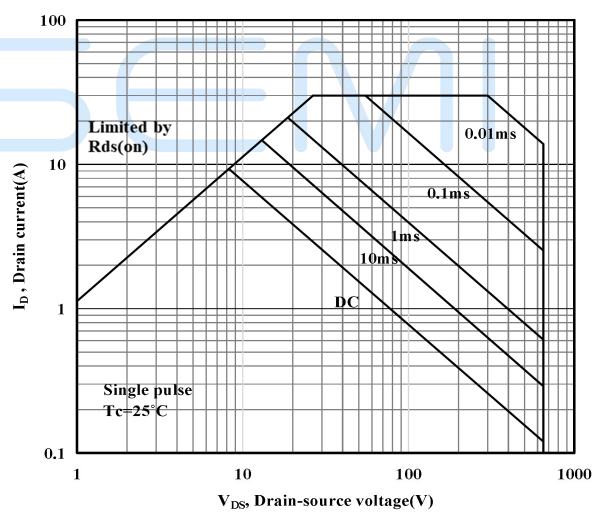
Note5: When mounted on 1 inch square copper board,  $t\leq 10\text{sec}$ . The value in any given application depends on the user's specific board design.

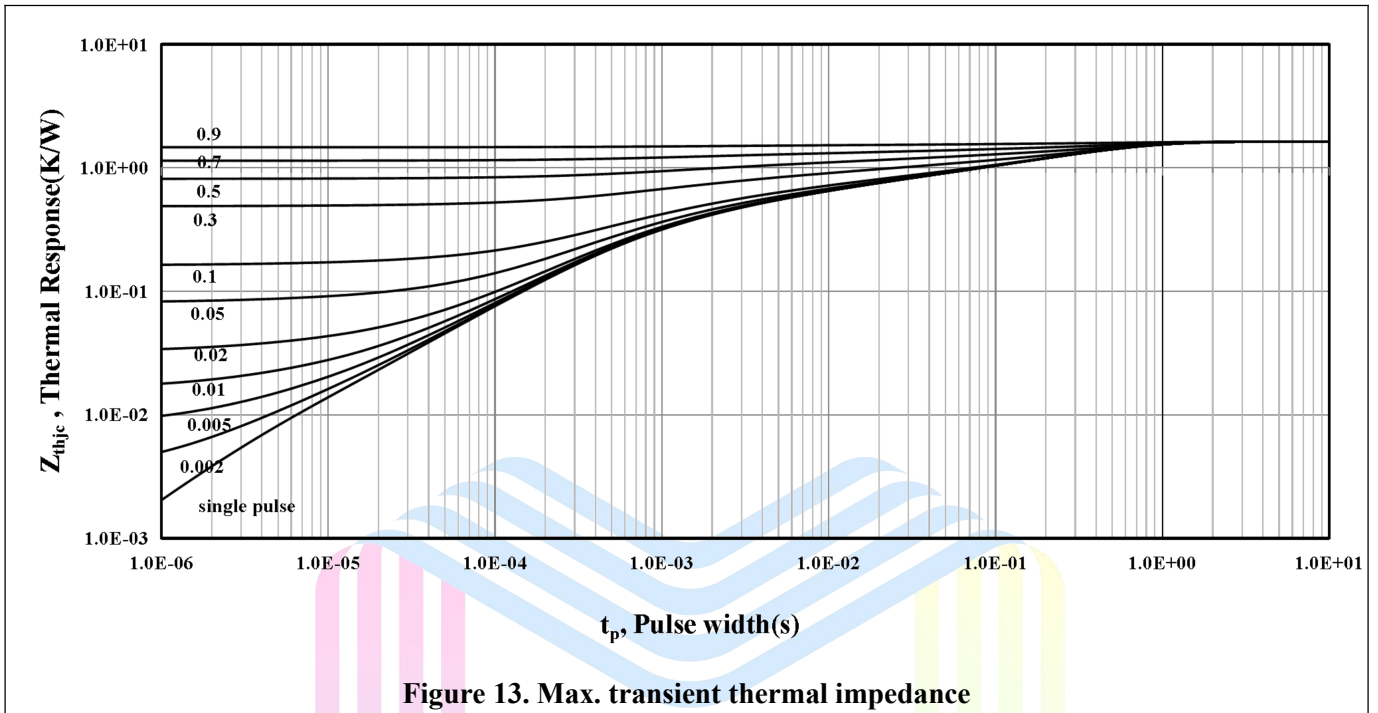
**Electrical Characteristics** ( $T_A = 25\text{ }^\circ\text{C}$ , unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>Statistic Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	650			V
Drain-Source Leakage Current	$I_{DSS}$	$V_{DS}=650V, V_{GS}=0V$			1	$\mu A$
Gate-Source Leakage Current	Forward	$I_{GSSF}, V_{GS}=30V, V_{DS}=0V$			100	nA
	Reverse	$I_{GSSR}, V_{GS}=-30V, V_{DS}=0V$			-100	
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	2.9		3.9	V
Drain-Source On-State Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=5A$		395	440	$m\Omega$
Gate Resistance	$R_G$	$F=1MHz, \text{Open Drain}$		5.48		$\Omega$
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{iss}$	$V_{DS}=100V$		688.5		pF
Output Capacitance	$C_{oss}$	$V_{GS}=0V$		57.44		pF
Reverse Transfer Capacitance	$C_{rss}$	$f=1MHz$		1.4		pF
Turn-on Delay Time	$t_{d(on)}$	$V_{DS}=400V$		16.3		ns
Rise Time	$t_r$	$I_D=5A$		11.9		
Turn-off Delay Time	$t_{d(off)}$	$R_G=25\Omega$		54.2		
Fall Time	$t_f$	$V_{GS}=10V$		8.7		
<b>Gate Charge Characteristics</b>						
Gate to Source Charge	$Q_{gs}$	$V_{DS}=400V$ $I_D=5A$ $V_{GS}=0 \text{ to } 10V$		4.6		nC
Gate to Drain Charge	$Q_{gd}$			5.7		
Gate Charge Total	$Q_g$			14.2		
Gate Plateau Voltage	$V_{plateau}$			5.45		V
<b>Reverse Diode Characteristics</b>						
Drain-Source Diode Forward Voltage	$V_{SD}$	$V_{GS}=0V, I_S=1A$		0.74		V
Reverse Recovery Time	$t_{rr}$	$V_R=400V$		272.4		ns
Reverse Recovery Charge	$Q_{rr}$	$I_S=5A$		2.2		$\mu C$
Peak Reverse Recovery Current	$I_{rrm}$	$di/dt=100A/\mu s$		16.3		A

## Electrical Characteristics Diagrams


**Figure 1. Typ. output characteristics**

**Figure 2. Typ. transfer characteristics**

**Figure 3. Typ. Capacitances**

**Figure 4. Typ. gate charge**

**Figure 5. Drain-source breakdown voltage**

**Figure 6. Drain-source on-state resistance**

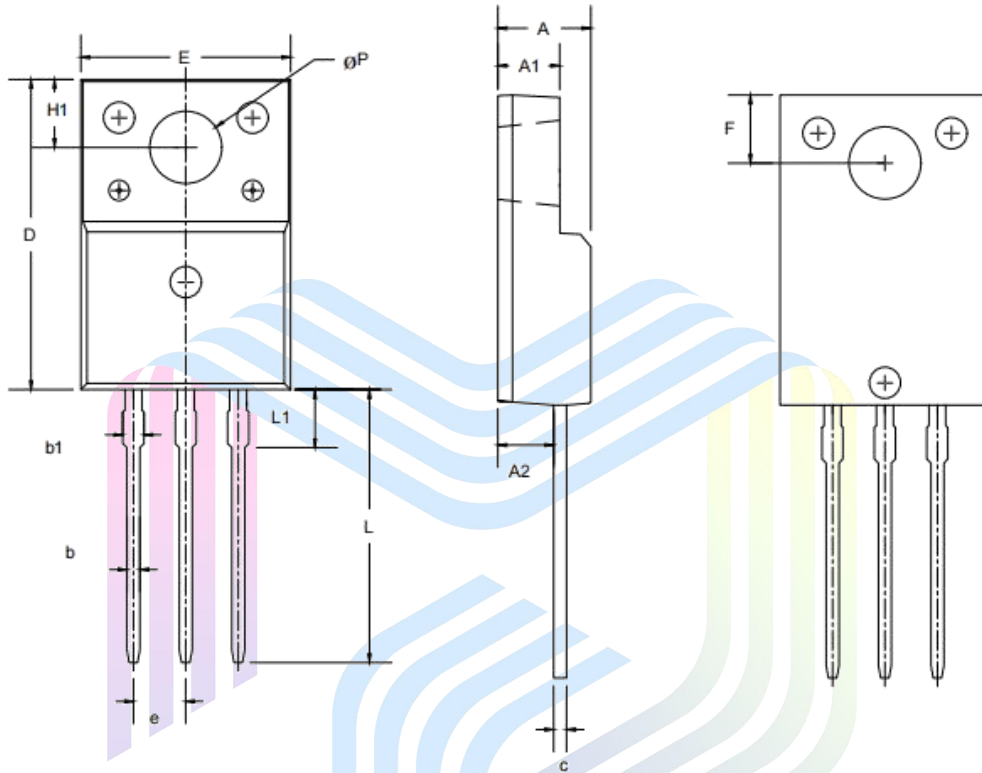

**Figure 7. Threshold voltage**

**Figure 8. Forward characteristic of body diode**

**Figure 9. Drain-source on-state resistance**

**Figure 10. Drain current Derating**

**Figure 11. Power Dissipation**

**Figure 12. Safe operation area  $T_c=25^\circ\text{C}$**



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## Mechanical Dimensions

### TO-220F Package Information



COMMON DIMENSIONS  
(UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	MAX
A	4.50	4.90
A1	2.30	2.80
A2	2.50	2.90
b	0.70	0.95
b1	1.08	1.55
c	0.40	0.70
D	15.00	16.17
E	9.50	10.50
e	2.54BSC	
F	2.80	3.65
H1	6.7REF	
L	12.50	13.50
L1	2.90	3.90
øP	2.90	3.40



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